



**NSAI**  
Standards

Irish Standard  
I.S. EN 60749-3:2017

# Semiconductor devices - Mechanical and climatic test methods - Part 3: External visual examination

**I.S. EN 60749-3:2017**

*Incorporating amendments/corrigenda/National Annexes issued since publication:*

The National Standards Authority of Ireland (NSAI) produces the following categories of formal documents:

I.S. xxx: Irish Standard — national specification based on the consensus of an expert panel and subject to public consultation.

S.R. xxx: Standard Recommendation — recommendation based on the consensus of an expert panel and subject to public consultation.

SWiFT xxx: A rapidly developed recommendatory document based on the consensus of the participants of an NSAI workshop.

*This document replaces/revises/consolidates the NSAI adoption of the document(s) indicated on the CEN/CENELEC cover/Foreword and the following National document(s):*

*NOTE: The date of any NSAI previous adoption may not match the date of its original CEN/CENELEC document.*

*This document is based on:*

EN 60749-3:2017

*Published:*

2017-06-16

*This document was published under the authority of the NSAI and comes into effect on:*

2017-07-04

ICS number:

31.080.01

NOTE: If blank see CEN/CENELEC cover page

NSAI  
1 Swift Square,  
Northwood, Santry  
Dublin 9

T +353 1 807 3800  
F +353 1 807 3838  
E standards@nsai.ie  
W NSAI.ie

Sales:  
T +353 1 857 6730  
F +353 1 857 6729  
W standards.ie

Údarás um Chaighdeáin Náisiúnta na hÉireann

## National Foreword

I.S. EN 60749-3:2017 is the adopted Irish version of the European Document EN 60749-3:2017, Semiconductor devices - Mechanical and climatic test methods - Part 3: External visual examination

This document does not purport to include all the necessary provisions of a contract. Users are responsible for its correct application.

For relationships with other publications refer to the NSAI web store.

**Compliance with this document does not of itself confer immunity from legal obligations.**

*In line with international standards practice the decimal point is shown as a comma (,) throughout this document.*

This page is intentionally left blank

EUROPEAN STANDARD

**EN 60749-3**

NORME EUROPÉENNE

EUROPÄISCHE NORM

June 2017

ICS 31.080.01

Supersedes EN 60749-3:2002

English Version

**Semiconductor devices - Mechanical and climatic test methods -  
Part 3: External visual examination  
(IEC 60749-3:2017)**

Dispositifs à semiconducteurs - Méthodes d'essais  
mécaniques et climatiques - Partie 3: Examen visuel  
externe  
(IEC 60749-3:2017)

Halbleiterbauelemente - Mechanische und klimatische  
Prüfverfahren - Teil 3: Äußere Sichtprüfung  
(IEC 60749-3:2017)

This European Standard was approved by CENELEC on 2017-04-07. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the CEN-CENELEC Management Centre or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the CEN-CENELEC Management Centre has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Bulgaria, Croatia, Cyprus, the Czech Republic, Denmark, Estonia, Finland, Former Yugoslav Republic of Macedonia, France, Germany, Greece, Hungary, Iceland, Ireland, Italy, Latvia, Lithuania, Luxembourg, Malta, the Netherlands, Norway, Poland, Portugal, Romania, Serbia, Slovakia, Slovenia, Spain, Sweden, Switzerland, Turkey and the United Kingdom.



European Committee for Electrotechnical Standardization  
Comité Européen de Normalisation Electrotechnique  
Europäisches Komitee für Elektrotechnische Normung

**CEN-CENELEC Management Centre: Avenue Marnix 17, B-1000 Brussels**

## **EN 60749-3:2017**

### **European foreword**

The text of document 47/2345/FDIS, future edition 2 of IEC 60749-3, prepared by IEC/TC 47 "Semiconductor devices" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 60749-3:2017.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2018-01-07
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2020-04-07

This document supersedes EN 60749-3:2002.

Attention is drawn to the possibility that some of the elements of this document may be the subject of patent rights. CENELEC shall not be held responsible for identifying any or all such patent rights.

### **Endorsement notice**

The text of the International Standard IEC 60749-3:2017 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following note has to be added for the standard indicated :

IEC 60749-9	NOTE	Harmonized as EN 60749-9.
-------------	------	---------------------------

## Annex ZA (normative)

### Normative references to international publications with their corresponding European publications

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: [www.cenelec.eu](http://www.cenelec.eu).

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 61340-5-1	-	Electrostatics - Part 5-1: Protection of electronic devices from electrostatic phenomena - General requirements	EN 61340-5-1	-
IEC 62483	-	Environmental acceptance requirements for tin whisker susceptibility of tin and tin alloy surface finishes on semiconductor devices	-	-

This page is intentionally left blank





**IEC 60749-3**

Edition 2.0 2017-03

# **INTERNATIONAL STANDARD**

---

**Semiconductor devices – Mechanical and climatic test methods –  
Part 3: External visual examination**





**THIS PUBLICATION IS COPYRIGHT PROTECTED**

**Copyright © 2017 IEC, Geneva, Switzerland**

All rights reserved. Unless otherwise specified, no part of this publication may be reproduced or utilized in any form or by any means, electronic or mechanical, including photocopying and microfilm, without permission in writing from either IEC or IEC's member National Committee in the country of the requester. If you have any questions about IEC copyright or have an enquiry about obtaining additional rights to this publication, please contact the address below or your local IEC member National Committee for further information.

IEC Central Office  
3, rue de Varembe  
CH-1211 Geneva 20  
Switzerland

Tel.: +41 22 919 02 11  
Fax: +41 22 919 03 00  
[info@iec.ch](mailto:info@iec.ch)  
[www.iec.ch](http://www.iec.ch)

**About the IEC**

The International Electrotechnical Commission (IEC) is the leading global organization that prepares and publishes International Standards for all electrical, electronic and related technologies.

**About IEC publications**

The technical content of IEC publications is kept under constant review by the IEC. Please make sure that you have the latest edition, a corrigenda or an amendment might have been published.

**IEC Catalogue - [webstore.iec.ch/catalogue](http://webstore.iec.ch/catalogue)**

The stand-alone application for consulting the entire bibliographical information on IEC International Standards, Technical Specifications, Technical Reports and other documents. Available for PC, Mac OS, Android Tablets and iPad.

**IEC publications search - [www.iec.ch/searchpub](http://www.iec.ch/searchpub)**

The advanced search enables to find IEC publications by a variety of criteria (reference number, text, technical committee,...). It also gives information on projects, replaced and withdrawn publications.

**IEC Just Published - [webstore.iec.ch/justpublished](http://webstore.iec.ch/justpublished)**

Stay up to date on all new IEC publications. Just Published details all new publications released. Available online and also once a month by email.

**Electropedia - [www.electropedia.org](http://www.electropedia.org)**

The world's leading online dictionary of electronic and electrical terms containing 20 000 terms and definitions in English and French, with equivalent terms in 16 additional languages. Also known as the International Electrotechnical Vocabulary (IEV) online.

**IEC Glossary - [std.iec.ch/glossary](http://std.iec.ch/glossary)**

65 000 electrotechnical terminology entries in English and French extracted from the Terms and Definitions clause of IEC publications issued since 2002. Some entries have been collected from earlier publications of IEC TC 37, 77, 86 and CISPR.

**IEC Customer Service Centre - [webstore.iec.ch/csc](http://webstore.iec.ch/csc)**

If you wish to give us your feedback on this publication or need further assistance, please contact the Customer Service Centre: [csc@iec.ch](mailto:csc@iec.ch).



**IEC 60749-3**

Edition 2.0 2017-03

# **INTERNATIONAL STANDARD**

---

**Semiconductor devices – Mechanical and climatic test methods –  
Part 3: External visual examination**

INTERNATIONAL  
ELECTROTECHNICAL  
COMMISSION

---

ICS 31.080.01

ISBN 978-2-8322-4001-4

**Warning! Make sure that you obtained this publication from an authorized distributor.**

## CONTENTS

FOREWORD.....	3
1 Scope.....	5
2 Normative references .....	5
3 Terms and definitions .....	5
4 Test apparatus .....	5
5 Procedure.....	5
6 Failure criteria .....	6
7 Summary .....	6
Annex A (informative) External visual report form/checklist (example only – not a mandatory template) .....	7
A.1 Leads.....	7
A.2 Lead finish .....	8
A.3 Moulding and mould compound.....	8
A.4 Critical sealant.....	9
A.5 Attachments.....	9
A.6 Marking.....	9
A.7 Solder Balls .....	10
A.8 Substrate .....	10
A.9 Exposed (Backside) Silicon .....	10
Bibliography.....	11

## INTERNATIONAL ELECTROTECHNICAL COMMISSION

---

### SEMICONDUCTOR DEVICES – MECHANICAL AND CLIMATIC TEST METHODS –

#### Part 3: External visual examination

#### FOREWORD

- 1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as “IEC Publication(s)”). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
- 2) The formal decisions or agreements of IEC on technical matters express, as nearly as possible, an international consensus of opinion on the relevant subjects since each technical committee has representation from all interested IEC National Committees.
- 3) IEC Publications have the form of recommendations for international use and are accepted by IEC National Committees in that sense. While all reasonable efforts are made to ensure that the technical content of IEC Publications is accurate, IEC cannot be held responsible for the way in which they are used or for any misinterpretation by any end user.
- 4) In order to promote international uniformity, IEC National Committees undertake to apply IEC Publications transparently to the maximum extent possible in their national and regional publications. Any divergence between any IEC Publication and the corresponding national or regional publication shall be clearly indicated in the latter.
- 5) IEC itself does not provide any attestation of conformity. Independent certification bodies provide conformity assessment services and, in some areas, access to IEC marks of conformity. IEC is not responsible for any services carried out by independent certification bodies.
- 6) All users should ensure that they have the latest edition of this publication.
- 7) No liability shall attach to IEC or its directors, employees, servants or agents including individual experts and members of its technical committees and IEC National Committees for any personal injury, property damage or other damage of any nature whatsoever, whether direct or indirect, or for costs (including legal fees) and expenses arising out of the publication, use of, or reliance upon, this IEC Publication or any other IEC Publications.
- 8) Attention is drawn to the Normative references cited in this publication. Use of the referenced publications is indispensable for the correct application of this publication.
- 9) Attention is drawn to the possibility that some of the elements of this IEC Publication may be the subject of patent rights. IEC shall not be held responsible for identifying any or all such patent rights.

International Standard IEC 60749-3 has been prepared by IEC technical committee 47: Semiconductor devices.

This second edition cancels and replaces the first edition published in 2002. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) reference to the need for ESD protection;
- b) inclusion of information on the phenomenon of tin whiskers;
- c) inclusion of an optional report form/checklist.

The text of this standard is based on the following documents:

FDIS	Report on voting
47/2345/FDIS	47/2370/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 60749 series, published under the general title *Semiconductor devices – Mechanical and climatic test methods*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

## SEMICONDUCTOR DEVICES – MECHANICAL AND CLIMATIC TEST METHODS –

### Part 3: External visual examination

#### 1 Scope

The purpose of this part of IEC 60749 is to verify that the materials, design, construction, markings, and workmanship of a semiconductor device are in accordance with the applicable procurement document. External visual inspection is a non-destructive test and applicable for all package types. The test is useful for qualification, process monitor, or lot acceptance.

#### 2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61340-5-1, *Electrostatics – Part 5-1: Protection of electronic devices from electrostatic phenomena – General requirements*

IEC 62483, *Environmental acceptance requirements for tin whisker susceptibility of tin and tin alloy surface finishes on semiconductor devices*

#### 3 Terms and definitions

No terms and definitions are listed in this document.

ISO and IEC maintain terminological databases for use in standardization at the following addresses:

- IEC Electropedia: available at <http://www.electropedia.org/>
- ISO Online browsing platform: available at <http://www.iso.org/obp>

#### 4 Test apparatus

Apparatus used in this test shall be capable of demonstrating device conformance to the applicable requirements, which may include optical equipment capable of magnification to resolve features between > 0,5 mm to 10 mm. A lense magnification between 3× and 10× and a relatively large and accessible field of view with an illuminated ring magnifier is typically used. Where visual observation requires clarification, a higher magnification (up to x30) can be used. Illumination should be in the range between 1,000 to 10,000 lux in an ambient overhead lighting environment of greater than 200 lux.

#### 5 Procedure

The device shall be examined in accordance with the requirements of the relevant specification and the criteria listed in Clause 6. Where adherence of foreign material is in question, devices may be subjected to a clean filtered air stream (suction or expulsion) of

This is a free preview. Purchase the entire publication at the link below:

[Product Page](#)

- 
- [Looking for additional Standards? Visit Intertek Inform Infostore](#)
  - [Learn about LexConnect, All Jurisdictions, Standards referenced in Australian legislation](#)
-